

Spin-on Glass NDG-5000R; NDG-5000

Elements of Interest Si, O	Key Element atoms/cm³ N/A	Key Element % in Film N/A
Viscosity 0.90 +/- 0.15 cps	Thickness Coats 4400 Å (440 nm) at 4000 rpm	Shelf Life 20°C 3 months 4°C 9 months

Benefits

- Simple method to add Oxide layers
- Low temperature approach to silicon oxide layer formation
- Lower Maintenance and Cost of Ownership
- High purity materials
- Uniform Coatings
- Basic composition that other elements can be easily added to
- Stable Processing Independent of Flow Rates

Typical Application

This is a non-doping glass that is used for coating with a silica film (SiO₂). When baked at 250°C it gives a low density film that continues to become increasingly dense as bakes continue to 600°C or higher. We recommend baking at least as the highest temperature in the process. The lower density materials work well for bonding processes.

The silica formed films have high melting points. Other elements can be added to lower the melting point if that is desired. Sometimes elements are added to change the refractive index or other properties.

Packaging

- 240ml
- 500ml
- 1 l
- 2.5 l
- 4 l

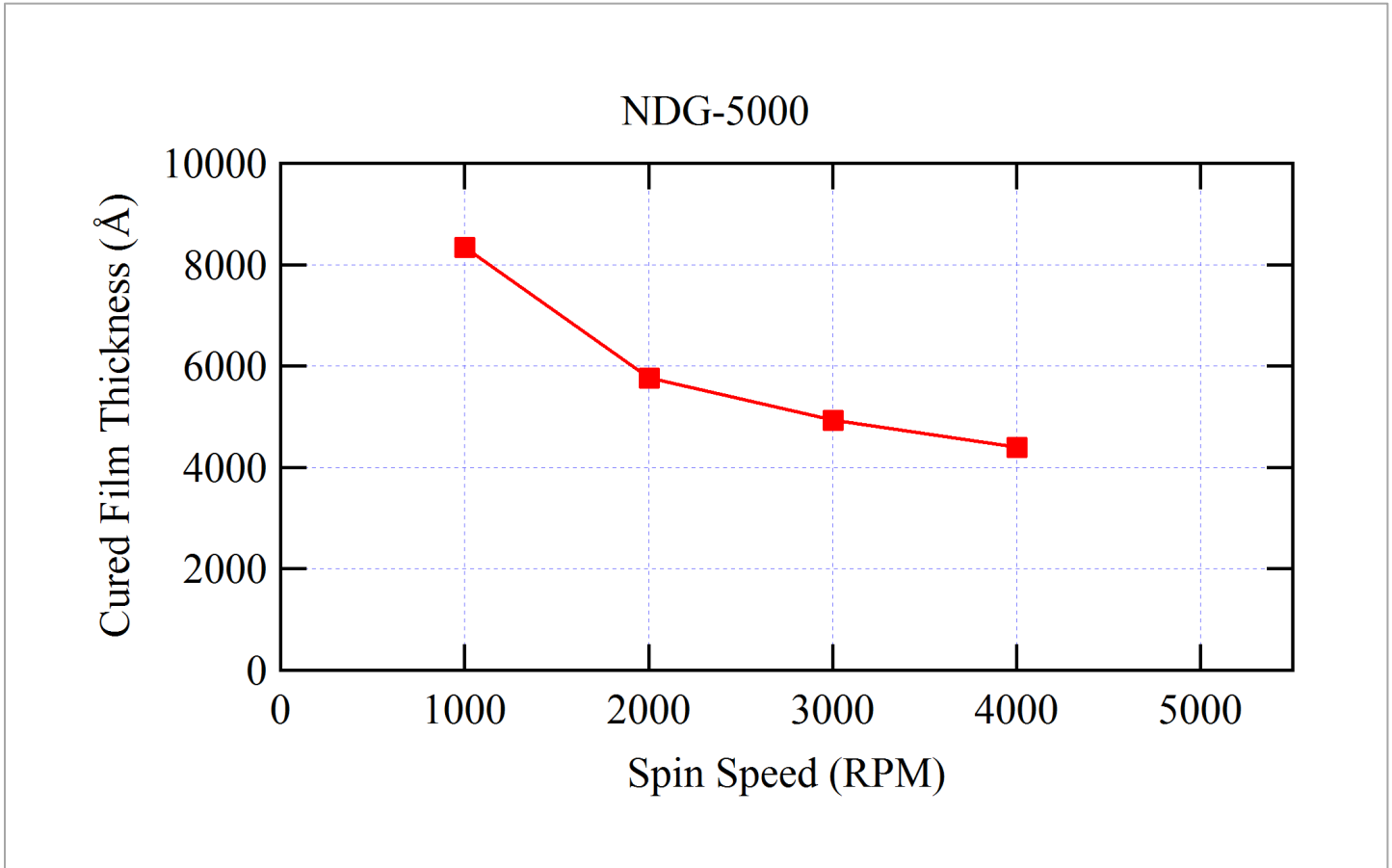
Alternative Products

NDG-2000
NDG-7000

Alternate Elements

- Pb
- Ge
- Bismuth
- Tin
- Blends of two or more elements
- Other elements available for compound semiconductor use

Spin-on Glass NDG-5000R; NDG-5000



Although all statement and information presented in this document are believed to be accurate and reliable, they are presented without warranty or guarantee of any kind, expressed or implied. Information presented does not relieve the end user from carrying out their own tests to determine suitability for use in their application. User assumes all risk and liability for use product or information and results obtained. Suggestions for use of material and processes are made without representation or warranty that any such is free from patent infringement and are not recommendations for patent infringement. Please see MSDS for information regarding health and safety of material use.